



Final Product/Process Change Notification

Document #:FPCN23597XN

Issue Date:20 Mar 2026

Title of Change:	Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - TCA0372B, MC33072, MC33272A families; EPI80 and EPI44 technology	
Proposed First Ship date:	27 Jun 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact	
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Material Change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic	None	
Description and Purpose:		
Conversion of select onsemi Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter.		
The purpose is to increase the wafer fab productivity.		
The 200mm wafer process at Roznov is the same as the 150mm process, with no changes to electrical and reliability performances of the products.		
This is a change in wafer diameter only; there will be no changes to assembly or test locations as a result of this change.		
	From	To
Wafer size	150 mm	200 mm
There is no product marking change as a result of this change		



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Reliability Data Summary:

DEVICE NAME: MC33274ADTBR2G

RRF#: 100944

PACKAGE: TSSOP14

Test	Specification	Condition	Interval	Result
HTOL	JESD22 A108	Ta= 110°C	1008 hrs	0/80
HAST	JESD22 A110	110°C/85%	264 hrs	0/240
PC	JESD22 A113 J-STD-020	SMD only, Test MSL=1, @260°C		Pass
TC	JESD22 A104	Test @ -65°C to +150°C	500cyc	0/240
Wire Bond Shear	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		Pass
Wire bond pull	M883 Method 2011	3gm Pull Force Min After TC		Pass

QV DEVICE NAME : ULN2003ADR2G

RMS# 68977

PACKAGE: SOIC16

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C	2016 hrs	0/240
PC	JA112 JA113	SMD only, Test @ 0 & EP		0/372
SAT		Test pre- and post- PC		pass
ELFR	JA018	TA = 125°C for 48 hrs	48hrs	0/2400
TC	JA104	Test @ R	1000cyc	0/270
BS	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		pass
BPS	M883 Method 2011	3gm Pull Force Min After TC		pass
ESD HBM	AEC-Q100-002	c = 0, Test @ R	2kV	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1.5kV	0/3
ED	ON Data Sheet	Cpk > 1.67 Test @ R, H, C	Cpk>1.67	pass
LU	AEC-Q100-004	Test @ EP; Test & Stress @ R	LU+>100mA LU->100mA	0/6

DEVICE NAME: TCA0372BDWR2G

RMS# 100944

PACKAGE: SOIC 16W

Test	Specification	Condition	Interval	Result
HTOL	JESD22 A108	Ta= 110°C	1008 hrs	0/80
HAST	JESD22 A110	110°C/85%	264 hrs	0/240
PC	JESD22 A113 J-STD-020	SMD only, Test MSL=3, @260°C		Pass
TC	JESD22 A104	Test @ -65°C to +150°C	500cyc	0/240
Wire Bond Shear	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		Pass
Wire bond pull	M883 Method 2011	3gm Pull Force Min After TC		Pass



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QV DEVICE NAME: LM317BD2TG

RMS# 67729

PACKAGE: D2PAK

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C	1008 hrs	0/240
PC	JA112 JA113	SMD only, Test @ 0 & EP		0/372
SAT		Test pre- and post- PC		pass
ELFR	JA018	TA = 125°C for 48 hrs	48hrs	0/2400
TC	JA104	Test @ R	500cyc	0/276
BS	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		pass
BPS	M883 Method 2011	3gm Pull Force Min After TC		pass
ESD HBM	AEC-Q100-002	c = 0, Test @ R	2kV	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1kV	0/3
ED	ON Data Sheet	Cpk > 1.67 Test @ R, H, C	Cpk>1.67	pass
LU	AEC-Q100-004	Test @ EP; Test & Stress @ R	LU+>100mA LU->100mA	0/6

Electrical Characteristics Summary:

Electrical characteristics are not impacted

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
TCA0372DWR2G	#NONE	TCA0372BDWR2G/LM317BD2TR4G
TCA0372BDWR2G	#NONE	TCA0372BDWR2G/LM317BD2TR4G
NCS2372DWR2G	#NONE	TCA0372BDWR2G/LM317BD2TR4G
MC34072VDR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC34072DR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC34072AMTTBG	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC34072ADR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC33272ADR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC33072DR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G
MC33072ADR2G	#NONE	MC33274ADTBR2G/ULN2003ADR2G